

# **RSM 2021**

#### 2021 IEEE REGIONAL SYMPOSIUM ON MICRO & NANOELECTRONICS



Ref. No.: EDS/RSM2021/SP01

12th February 2021

To Whom It May Concern, Dear Sir/Madam,

# Sponsorship for 2021 IEEE Regional Symposium on Micro & Nanoelectronics (IEEE-RSM 2021)

I am pleased to announce that the IEEE Regional Symposium on Micro & Nanoelectronics (IEEE-RSM 2021) will be held on 2<sup>nd</sup> to 4<sup>th</sup> August, 2021 virtually. The conference covers various issues and trends in the field of semiconductor electronics. The conference is organized by Electron Devices Chapter of IEEE Malaysia Section and technically co-sponsored by the IEEE Electron Devices Society. Registered and presented paper will be submitted for inclusion in IEEEXplore® and SCOPUS®.

The conference has been successful in attracting participants from universities and industries from all over Malaysia and Asia-Pacific countries.

On behalf of the organizing committee, I would like to extend our sincere welcome for your company to take this opportunity to put your name alongside the other contributing dignitaries. In order to ensure that both parties mutually benefit from the sponsorship, several forms of return can be offered such as the company logo printed prominently on the front cover of the proceedings, discounted fees for participants attending the conference or other arrangements that best suited to your company needs.

Please find the enclosed copy of the conference sponsorship proposal for your perusal. Your support is highly appreciated. Thank you.

Yours sincerely,

ASS. PROF. DR. AHMAD SABIRIN ZOOLFAKAR

Conference Chair IEEE-RSM 2021

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## 2021 IEEE REGIONAL SYMPOSIUM ON MICRO & NANOELECTRONICS





#### **BACKGROUND**

We are pleased to invite you to the 13th 2021 IEEE Regional Symposium on Micro and Nanoelectronics (RSM). This bi-annual technical conference since 1997 aims at bringing together researchers from industry and academia to gather and explore various issues and trends in the field of semiconductor electronics. This is the 13th RSM organized by the Electron Devices Chapter of IEEE Malaysia Section and technically co-sponsored by the IEEE Electron Devices Society. Over the last eighteen years, RSM conference series has become the prominent international forum on semiconductor electronics embracing all aspects of the semiconductor technology from circuit device, modeling and simulation, photonics and sensor technology, MEMS technology, process and fabrication, packaging technology and manufacturing, failure analysis and reliability, material and devices and nanoelectronics. Registered and presented paper will be submitted for inclusion in IEEE Xplore database.

ORGANIZER : Electron Devices Malaysia Chapter,

IEEE Malaysia Section

CO-SPONSORED : IEEE Electron Devices Society

CONFERENCE VENUE : Virtual Platform

DATE : 2-4th August, 2021

NO. OF PARTICIPANTS : 150

INVITED SPEAKER : 3 keynote speeches

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# **SPONSORSHIP PACKAGES**

| No | BENEFITS   | DIAMOND<br>RM10,000 | PLATINUM<br>RM8,000 | GOLD<br>RM6,000 | SILVER<br>RM4,000 | BRONZE<br>RM2,000 | COPPER any amount |
|----|--|---------------------|---------------------|-----------------|-------------------|-------------------|-------------------|
|    |  | KW110,000           | KW10,000            | KW10,000        | KW14,000          | KW12,000          | any amount        |
| 1  | Invited speech in<br>the evening session<br>(1st day)  | •                   |                     |                 |                   |                   |                   |
| 2  | Invited speech in the evening session (2 <sup>nd</sup> day)  |                     | •                   |                 |                   |                   |                   |
| 3  | Sponsor company eligible to best oral presentation award   | •                   | •                   | •               |                   |                   |                   |
| 4  | Three (3) complimentary invitations for selected days and sessions*                                    | •                   |                     |                 |                   |                   |                   |
| 5  | Two (2)<br>complimentary<br>invitations for<br>selected days and<br>sessions*                          |                     | •                   |                 |                   |                   |                   |
| 6  | One (1) complimentary invitations for selected days and sessions*                                      |                     |                     | •               |                   |                   |                   |
| 7  | Sponsors<br>announcement of<br>company's virtual<br>booth during the<br>conference's                   | •                   | •                   | •               | •                 |                   |                   |
| 8  | Virtual booth with video display **  | •                   | •                   | •               | •                 |                   |                   |
| 9  | Company logo<br>featured in the<br>conference<br>communication<br>effort: pre & post<br>press/ website | •                   | •                   | •               | •                 | •                 |                   |
| 10 | Post event reference<br>of all sponsors in<br>the coverage in<br>media print or<br>newsletter          | •                   | •                   | •               | •                 | •                 | •                 |

<sup>\*</sup> Complimentary service that gives you the opportunity to invite clients, associates or suppliers to attend a conference's session.

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<sup>\*\*</sup> The virtual booth allows you to choose the company's videos/ recorded presentations option to customize your content.



Organization/

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# SPONSORSHIP APPLICATION FORM

Please complete and sign the application form and return it by email to edsmalaysia@gmail.com

| Company Name:   |                     |  |                        |                   |   |  |
|---|---------------------|--|------------------------|-------------------|---|--|
| Full address:   |                     |  |                        |                   |   |  |
| Phone:  |                     | Mobil<br>Facsi                             |                        | e:                |   |  |
| Contact Person:   |                     |  |                        | mile              |   |  |
| Email:  |                     |  | <b>'</b>               |                   |   |  |
| "I / We would like to company / organizati marked below:"                               |                     | agreed to participate                      | in IEEE-               |                   |   |  |
| ITEM  |                     | PRICE (RM)                                 |                        |                   | SELECTION (/)                             |  |
| Diamond   |                     | 10,000                                     |                        |                   |   |  |
| Platinum  |                     | 8,000                                      |                        |                   |   |  |
| Gold<br>Silver  |                     | 6,000                                      |                        |                   |   |  |
|   |                     | 4,000                                      |                        |                   |   |  |
| Bronze<br>Copper  |                     | 2,000<br>any amount                        |                        |                   |   |  |
|   | 4                   |  |                        | - et t            | the data on the Due                       |  |
| The applicant agrees Invoice. Applicant's s to be bound by all the returned to the RSM2 | ignature<br>terms a | below indicates that nd conditions of this | has read<br>form. This | l, unde<br>s form | erstands and agrees<br>must be signed and |  |
| Name (in capital lette  | rs):                | Date                                       |                        | :                 |   |  |
| Signature:  |                     |  | Stam                   |                   | np of the Company:                        |  |
|   |                     |  |                        | http:             | ://ieeemalaysia-eds.org                   |  |

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## **PAYMENT INFORMATION**

#### **GENERAL INFORMATION**

• All above rates are in Ringgit Malaysia (RM)

#### **PAYMENT DATELINES**

- Upon receipt of the signed application form and acceptance of terms and regulations, a pro-invoice will be sent by RSM2021 finance department.
- Payment is due 30 days of the pro-invoice date.

#### **PAYMENT METHODS**

• Payment upon receipt of pro-invoice (please indicate the pro-invoice number) by transfer to the following account:

Bank Account Details:

Bank: CIMB BANK

Branch: No. 33, Jalan SP 2/1, Taman Serdang Perdana, Tingkat Bawah &

Mezzanine, 43300 Seri Kembangan, Selangor

Account Holder: IEEE REGIONAL SYMPOSIUM ON MICRO AND

Account Number: 1215-0011247-05-9 (old) or 8002166678 (new)

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